

**SOLDERING GUIDANCE
(EDLC Series)**

※ The document is the guidance when soldering VINATech's EDLC onto a PCB board.

1. Note

- If the soldering temperature is too high or soldering time is too long, the characteristic of the product can be deteriorated or swollen.
- If the soldering temperature is high or soldering time is long, sleeve can be cracked, dented, or melted.
- The soldering process must be proceeded after connecting the PCB and the product.
- Also, when connecting PCB and the product, the product must be covered up the sleeve.
- Do not dip the product into melted solder.
- During the soldering process, melted lead must be contacted with terminal of the product only.

2. Wave soldering

Recommended condition

- Solder composition : 99.3Sn–0.7Cu
- Solder pot temperature : 250~270°C
- Max. Exposure time : 10 sec
- Max. preheat temperature (PCB bottom) : 160°C
- Max. preheat time (above temperature 100°C) : 60 sec

3. Manual soldering

Recommended condition

- Temperature of the soldering rod tip : 350°C (Pb solder) and 400°C (Pb-free solder)
- Max. soldering duration : 5sec

Do not touch the product with the soldering rod.

4. Reflow soldering

Do not use reflow soldering of the product.

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